

PRODUCT CHARACTERISTICS

V_{DSS}	1500V
$R_{DS(ON)}$ Typ(@ $V_{GS}=10V$)	6 Ω
Q_g @typ	36nC
I_D	3A

APPLICATIONS

- * High efficiency switch mode power supplies
- * Electronic lamp ballasts based on half bridge
- * LED power supplies

FEATURE

- * High Switching Speed
- * Improved dv/dt capability

ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT3N150V	TO-3PF	30 pieces/Tube

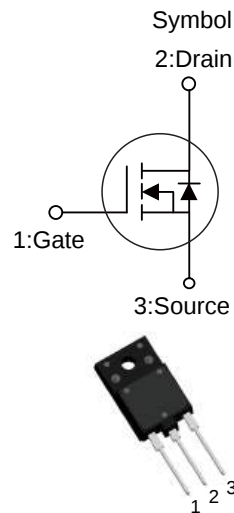
ABSOLUTE MAXIMUM RATINGS($T_A=25^{\circ}C$, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DSS}	1500	V
Gate-Source Voltage	V_{GSS}	± 30	V
Drain Current Continuous(@ $V_{GS}=10V$, $T_A=25^{\circ}C$)	I_D	3	A
Drain Current Pulsed	I_{DM}	12	A
Avalanche Energy *	E_{AS}	180	mJ
Power Dissipation	P_D	90	W
Junction Temperature	T_J	+150	$^{\circ}C$
Storage Temperature	T_{STG}	-55~ +150	$^{\circ}C$

THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Case	R_{thJC}	1.38	$^{\circ}C/W$

Note: * EAS condition: $T_J=25^{\circ}C$, $V_{DD}=100V$, $V_G=10V$, $L=10mH$, $R_g=25\Omega$



TO-3PF

■ ELECTRICAL CHARACTERISTICS ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	V _{DSS}	V _{GS} =0V, I _D =250μA	1500	-	-	V
Drain to Source Leakage Current	I _{DSS}	V _{DS} =1500V, V _{GS} =0V	-	-	1	μA
Gate to Source Forward Leakage	I _{GSS(F)}	V _{DS} =0V, V _{GS} =+30V	-	-	100	nA
Gate to Source Reverse Leakage	I _{GSS(R)}	V _{DS} =0V, V _{GS} =-30V	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =1.5A	-	6	8.2	Ω
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250μA	2.5	4	4.5	V
Dynamic characteristics						
Gate capacitance	R _g	V _{GS} =0V, V _{DS} =0V ,f=1.0MHz	-	1.2	-	Ω
Forward Transconductance	g _{fs}	V _{DS} =10V, I _D =1A	10	-	-	S
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V f=1.0MHz	-	1000	-	pF
Output Capacitance	C _{oss}		-	89	-	pF
Reverse Transfer Capacitance	C _{rss}		-	8.2	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	t _{d(ON)}	I _D =3 A, V _{DS} =750V R _G =4.7Ω ,V _{GS} =10V	-	25	-	ns
Rise Time	t _r		-	48	-	ns
Turn-off Delay Time	t _{d(OFF)}		-	57	-	ns
Fall Time	t _f		-	52	-	ns
Total Gate Charge	Q _g	I _D =3A, V _{DS} =750V V _{GS} =10V	-	36	-	nC
Gate to Source Charge	Q _{gs}		-	9.5	-	nC
Gate to Drain("Miller") Charge	Q _{gd}		-	12	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	I _s		-	-	3	A
Maximum Pulsed Current(Body Diode)	I _{SM}		-	-	12	A
Diode Forward Voltage	V _{SD}	I _{SD} =1A, V _{GS} =0V	-	0.78	1.2	V
Reverse Recovery Time	t _{rr}	I _{SD} =3 A, T _J =25 °C	-	255	-	ns
Reverse Recovery Charge	Q _{rr}	dI /dt=100A/μs	-	1100	-	nC

■ TYPICAL CHARACTERISTICS

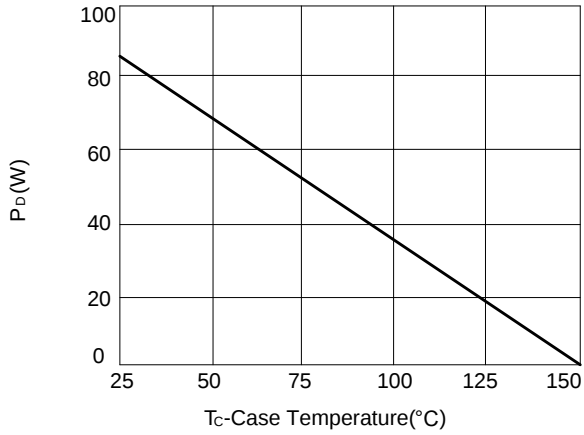


Figure 1: Power Dissipation vs Case Temperature

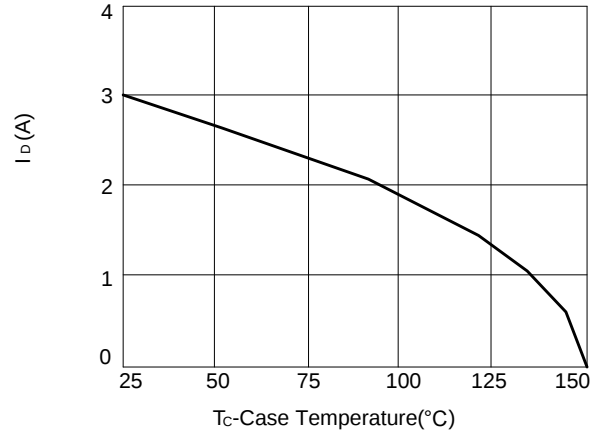


Figure 2: Maximum Continuous Drain Current vs Tc

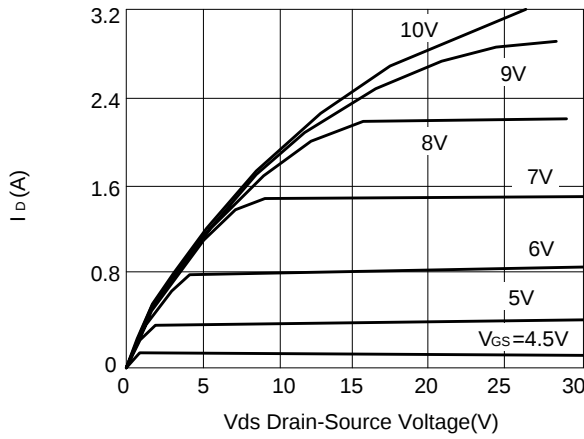


Figure 3: Output Characteristics

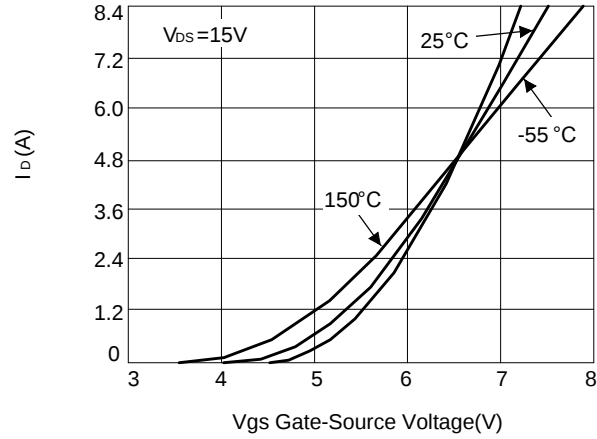


Figure 4: Transfer Characteristics

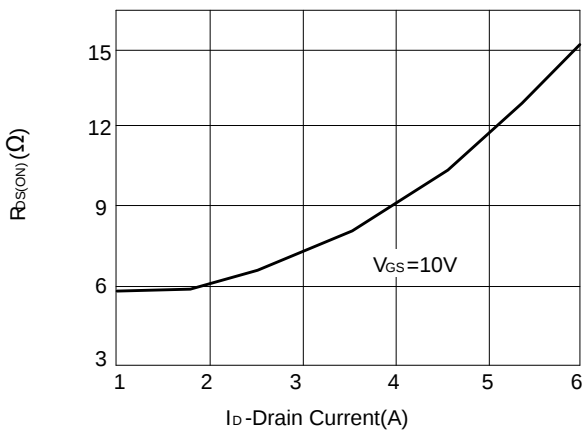


Figure 5: Drain to Source On-Resistance vs Drain Current

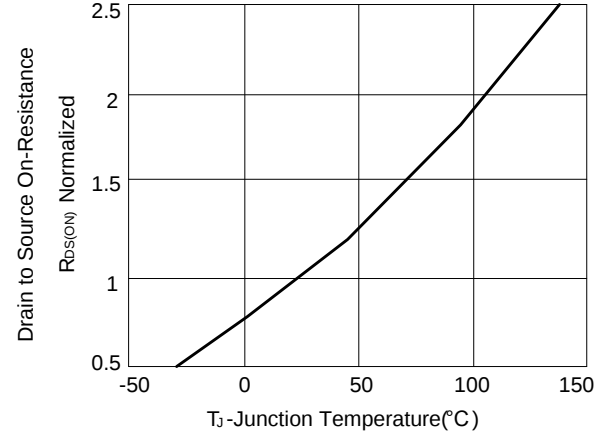


Figure 6: Power Dissipation vs Case Temperature

■ TYPICAL CHARACTERISTICS(Cont.)

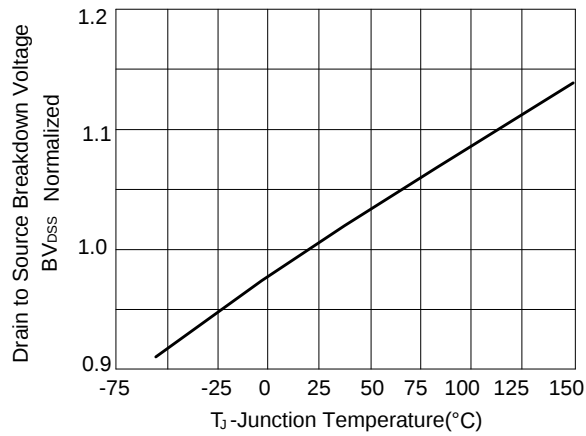


Figure 7: Breakdown Voltage vs Junction Temperature

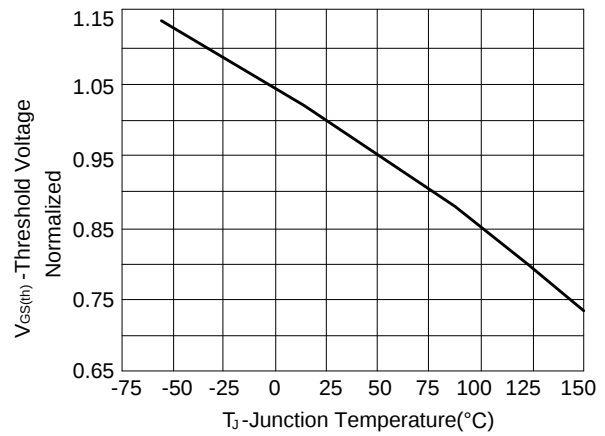


Figure 8: Threshold Voltage vs Junction Temperature

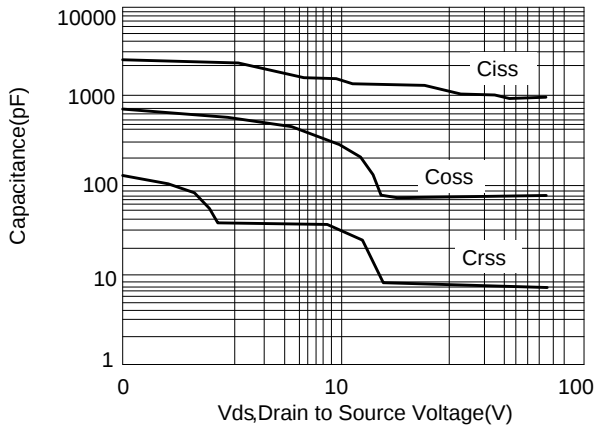


Figure 9: Capacitance vs V_{DS}

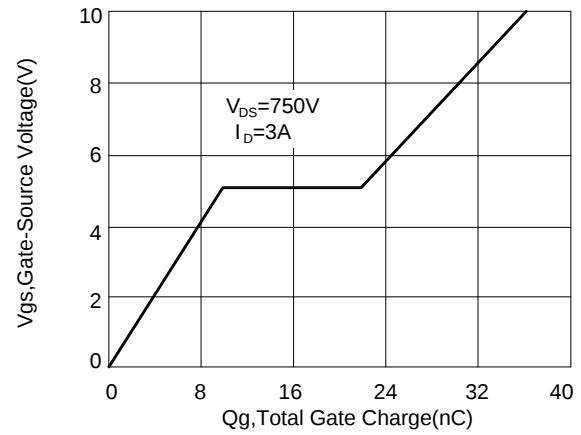


Figure 10: Typical Gate Charge

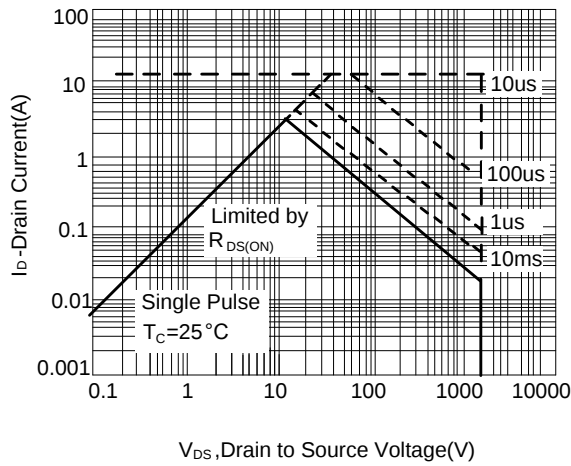


Figure 11: Power Dissipation vs Power Temperature

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